

60V N Channel+P Channel MOSFET

Features

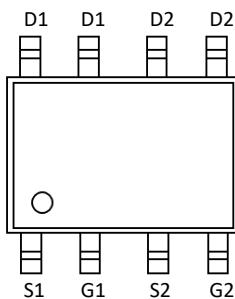
- High power and current handing capability
- Lead free product is acquired
- Surface mount package

Product Summary

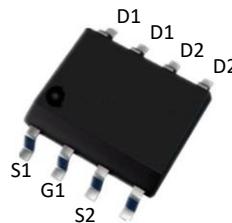
V_{DS}	$R_{DS(ON)} \text{ MAX}$	$I_D \text{ MAX}$
60V	90mΩ@10V	4A
	120mΩ@4.5V	
-60V	200mΩ@-10V	-2A
	300mΩ@-4.5V	

Application

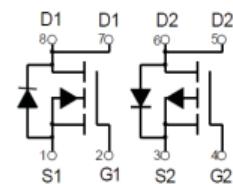
- Battery protection
- Load switch
- Power management



Marking and pin assignment



SOP-8 top view



Schematic diagram

Absolute Maximum Ratings ($TA=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	N-Channel	P-Channel	Unit
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Common Ratings ($TC=25^\circ\text{C}$ Unless Otherwise Noted)

V_{DS}	Drain-Source Breakdown Voltage	60	-60	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
T_J	Maximum Junction Temperature	150	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	$^\circ\text{C}$
I_S	Diode Continuous Forward Current	Tc=25°C 4	-2	A

Mounted on Large Heat Sink

I_{DM}	Pulse Drain Current Tested	Tc=25°C 15	-7	A
I_D	Continuous Drain Current@GS=10V	Tc=25°C 4	-2	A
P_D	Maximum Power Dissipation	Tc=25°C 2	2	W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient(*1 in2 Pad of 2-oz Copper), Max.)	62.5	62.5	$^\circ\text{C}/\text{W}$

N-Ch Electrical Characteristics (TJ=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ TJ = 25°C (unless otherwise stated)						
$BV_{(BR)DSS}$	Drain-Source Breakdown Voltage	$VGS=0V, ID=250\mu A$	60	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$VDS=60V, VGS=0V$	--	--	1	uA
I_{GSS}	Gate-Body Leakage Current	$VGS=\pm 20V, VDS=0V$	--	--	± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$VDS=VGS, ID=250\mu A$	1	1.5	2.5	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$VGS=10V, ID=3A$	--	58	90	mΩ
		$VGS=4.5V, ID=2A$	--	70	120	mΩ
Dynamic Electrical Characteristics @ TJ = 25°C (unless otherwise stated)						
C_{ISS}	Input Capacitance	$VDS=30V, VGS=0V, f=1MHz$	--	400	--	pF
C_{OSS}	Output Capacitance		--	28	--	pF
C_{RSS}	Reverse Transfer Capacitance		--	23	--	pF
Switching Characteristics						
Q_g	Total Gate Charge	$VDS=30V, ID=3A, VGS=10V$	--	9	--	nC
Q_{gs}	Gate Source Charge		--	1	--	nC
Q_{gd}	Gate Drain Charge		--	2.5	--	nC
$t_{d(on)}$	Turn-on Delay Time	$VDD=30V, ID=3A, VGS=10V, RG=2.3\Omega$	--	4	--	nS
t_r	Turn-on Rise Time		--	10	--	nS
$t_{d(off)}$	Turn-Off Delay Time		--	12.5	--	nS
t_f	Turn-Off Fall Time		--	1.8	--	nS
Source- Drain Diode Characteristics						
V_{SD}	Forward on voltage	$Tj=25^{\circ}C, Is=3A,$	--	--	1.2	V

P-Ch Electrical Characteristics (TJ=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ TJ = 25°C (unless otherwise stated)						
$BV_{(BR)DSS}$	Drain-Source Breakdown Voltage	$VGS=0V, ID=-250\mu A$	-60	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$VDS=-60V, VGS=0V$	--	--	-1	uA
I_{GSS}	Gate-Body Leakage Current	$VGS=\pm 20V, VDS=0V$	--	--	± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$VDS=VGS, ID=-250\mu A$	-1	-1.5	-2.5	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$VGS=-10V, ID=-3A$	--	160	200	$m\Omega$
		$VGS=-4.5V, ID=-2A$	--	200	300	$m\Omega$

Dynamic Electrical Characteristics @ TJ = 25°C (unless otherwise stated)

C_{iss}	Input Capacitance	$VDS=-30V, VGS=0V, f=1MHz$	--	430	--	pF
C_{oss}	Output Capacitance		--	33	--	pF
C_{rss}	Reverse Transfer Capacitance		--	22	--	pF

Switching Characteristics

Q_g	Total Gate Charge	$VDD=-30V, ID=-2A, VGS=-10V$	--	8.5	--	nC
Q_{gs}	Gate Source Charge		--	2.1	--	nC
Q_{gd}	Gate Drain Charge		--	1.6	--	nC
$t_{d(on)}$	Turn-on Delay Time	$VDD=-30V, ID=-1A, VGS=-10V, RG=6\Omega$	--	5.3	--	nS
t_r	Turn-on Rise Time		--	20	--	nS
$t_{d(off)}$	Turn-Off Delay Time		--	33	--	nS
t_f	Turn-Off Fall Time		--	10	--	nS

Source- Drain Diode Characteristics

V_{SD}	Forward on voltage	$Tj=25^\circ C, Is=-2A,$	--	--	-1.2	V
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N-Channel Typical Operating Characteristics

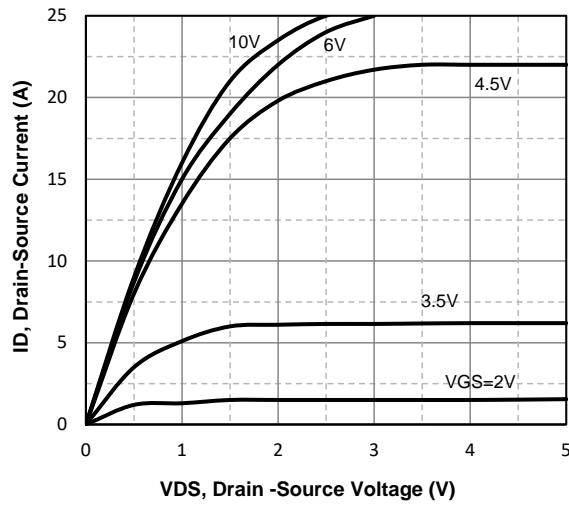


Fig1. Typical Output Characteristics

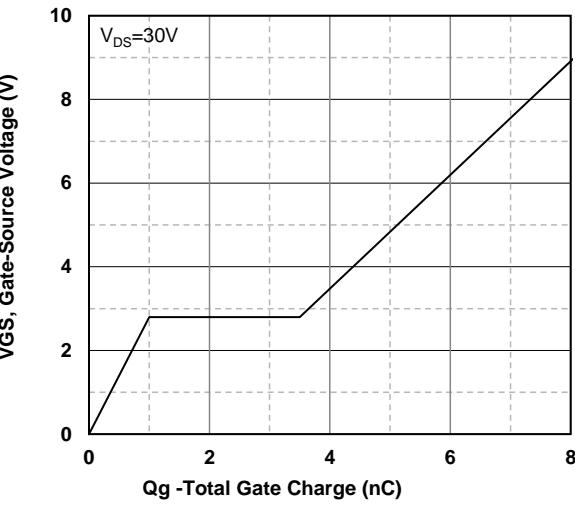


Fig2. Typical Gate Charge Vs.Gate-Source Voltage

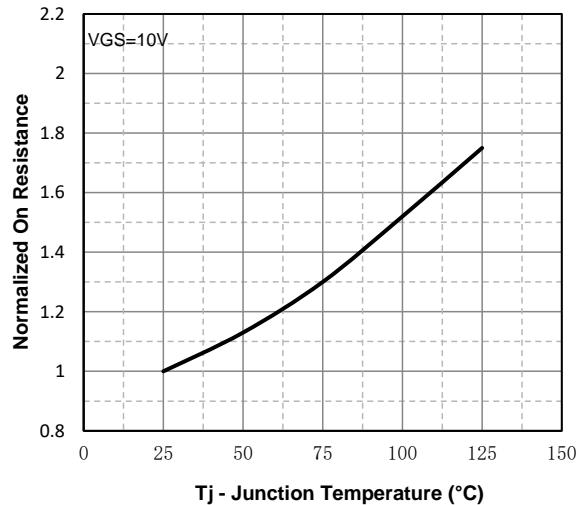


Fig3. Normalized On-Resistance Vs. Temperature

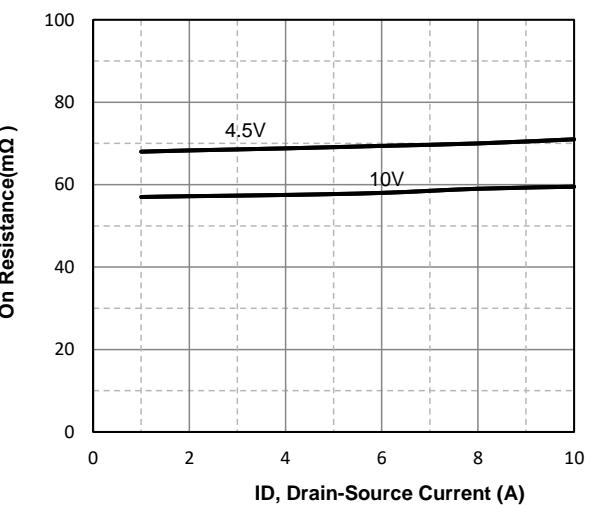


Fig4. On-Resistance Vs. Drain-Source Current

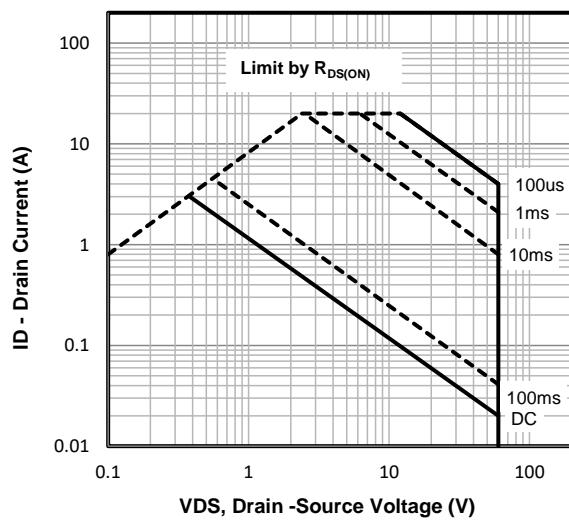


Fig5. Maximum Safe Operating Area

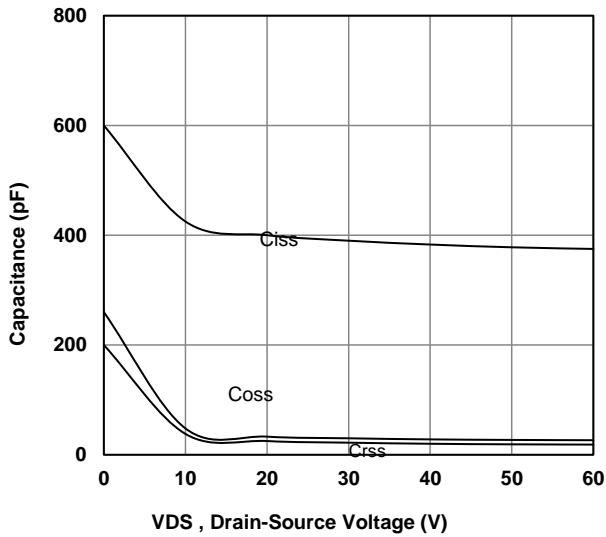


Fig6. Typical Capacitance Vs.Drain-Source Voltage

P-Channel Typical Operating Characteristics

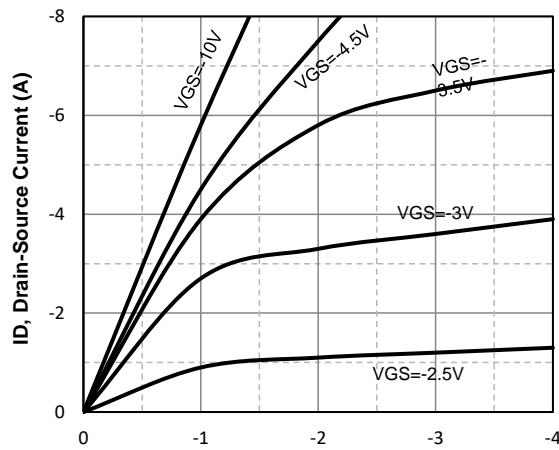


Fig1. Typical Output Characteristics

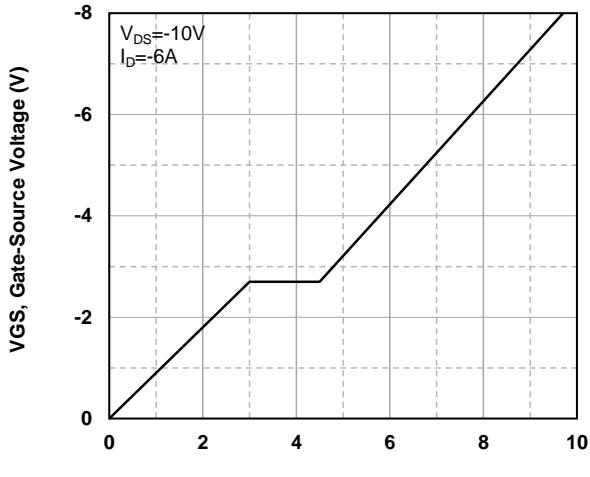


Fig2. Typical Gate Charge Vs.Gate-Source Voltage

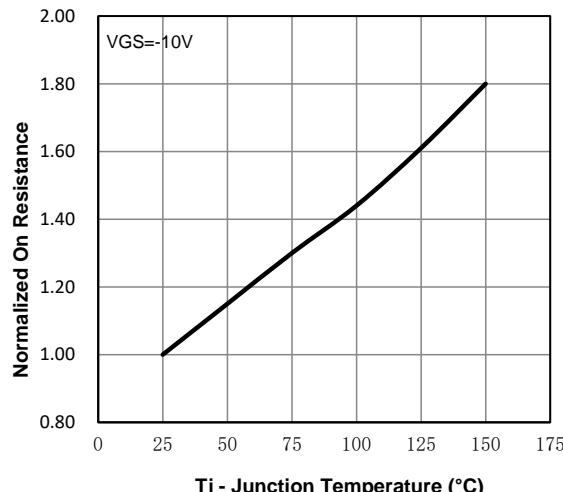


Fig3. Normalized On-Resistance Vs. Temperature

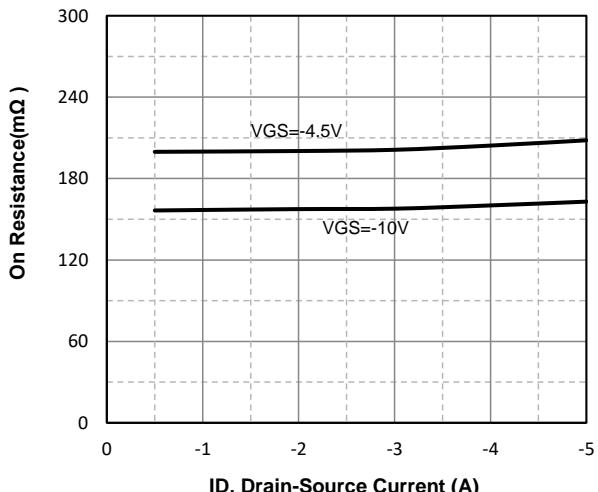


Fig4. On-Resistance Vs. Drain-Source Current

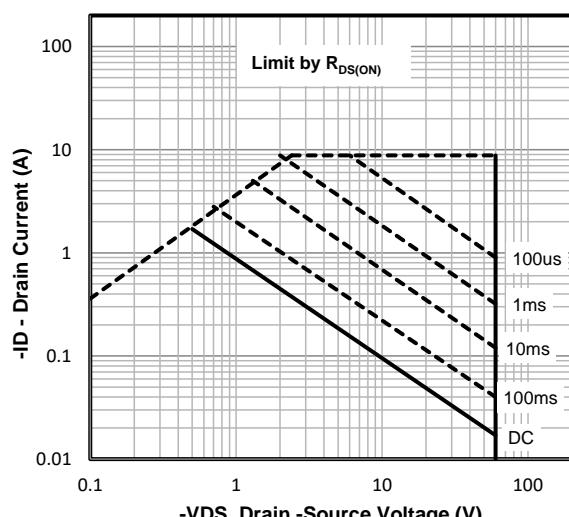


Fig5. Maximum Safe Operating Area

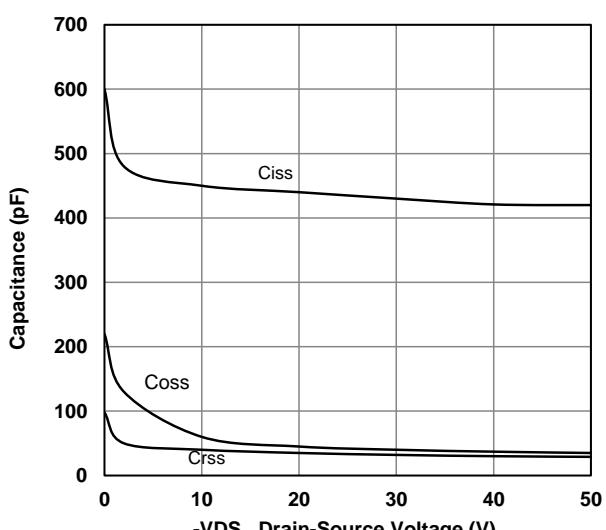
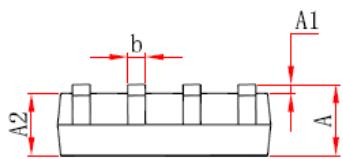
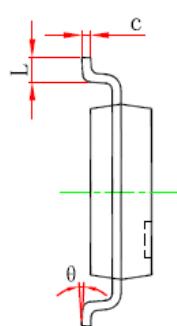
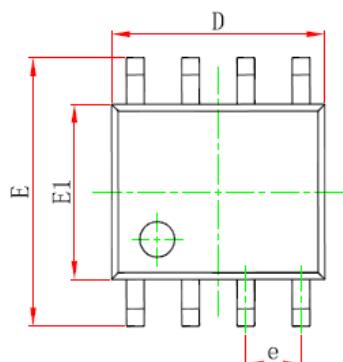


Fig6 Typical Capacitance Vs.Drain-Source Voltage

SOP-8 Package information

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.450	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.700	5.100	0.185	0.201
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°